METHOD FOR ROUTING A CHAMFERED SUBSTRATE

ABSTRACT

The invention relates to a method for routing a chamfered substrate (4).

This method is noteworthy in that it comprises the following steps consisting in:

- depositing a layer of a protective material on a peripheral annular zone of the said substrate (4), with the aid of a plasma,
- partially etching the said protective material with the aid of a plasma, so as to preserve a ring (60) of it on the front face (41) of the said substrate (4), this ring (60) extending at a distance from the edge (43) of the substrate, and so as thus to delimit an accessible peripheral annular zone (400'),
- etching a thickness of the material constituting the said substrate (4) to be routed, with the aid of a plasma level with the said accessible peripheral annular zone (400') of the substrate (4),
- removing the said ring of protective material (60) with the aid of a plasma.

Applications in the field of electronics, optics or optoelectronics.

Figure 6B